Product / Package Information

Package	LQFP
Body Size (mm)	14 X 14 X 1.4
Lead Count	100
Terminal Finish	100 Sn

Environmental Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	4.28E-01	88.0	880000	65.72	657167
Thermosets	Epoxy & Phenol resin	Proprietary	5.59E-02	11.5	115000	8.59	85880
Other inorganic materials	Carbon black	1333-86-4	2.43E-03	0.5	5000	0.37	3734
Subtotal			4.86 E-01	100.00	1000000	74.68	746781

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	1.35E-01	96.20	962000	20.68	206828
Copper & its alloys	Nickel	7440-02-0	4.20E-03	3.00	30000	0.64	6450
Copper & its alloys	Silicon	7440-21-3	9.09E-04	0.65	6500	0.14	1397
Copper & its alloys	Magnesium	7439-95-4	2.10E-04	0.15	1500	0.03	322
Subtotal			1.40 E-01	100.00	1000000	21.50	214998

Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious Metals	Silver	7440-22-4	1.04 E-03	100.0	1000000	0.16	1599

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	5.46 E-03	100.0	1000000	0.84	8393

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious Metals	Gold	7440-57-5	3.41E-03	99.00	990000	0.52	5235
Precious Metals	Palladium	7440-05-3	3.44E-05	1.00	10000	0.01	53
Subtotal			3.44 E-03	100.00	1000000	0.53	5288

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	1.24 E-02	100.0	1000000	1.90	18983

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	1.73E-03	66.34	663400	0.27	2661
Thermoset	Epoxy resin	Proprietary	1.46E-04	5.61	56100	0.02	225
Other organic materials	Aliphatic acid anhydride	Proprietary	1.46E-04	5.61	56100	0.02	225
Other organic materials	2,6 diglycidyl phenyl allyl ether oligomer	Proprietary	1.46E-04	5.61	56100	0.02	225
Other organic materials	Epoxy derivative	Proprietary	1.46E-04	5.61	56100	0.02	225
Other organic materials	1,4-bis(2,3-epoxypropoxy)butane	Proprietary	1.46E-04	5.61	56100	0.02	225
Other organic materials	Hexahydromethylphthalic anhydride	Proprietary	1.46E-04	5.61	56100	0.02	225
Subtotal	Subtotal		2.61 E-03	100.00	1000000	0.40	4012

			Weight (g)			Percentage (%)	PPM
Package Totals			**6.51 E-01**			100.00	1000000

Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.

ANALOG DEVICES